

INITIAL INFORMATION DATA SHEET

APPLICATION INFORMATION

Application Type:: Regular
Subject Matter:: Utility
Title:: High Performance FlipChip Package
That Incorporates Heat Removal With
Minimal Thermal Mismatch
Docket Number:: X-901 US
Request for Early Pub?:: No
Request for Non-Pub?:: Yes
Total Drawing Sheets:: 3
Small Entity?:: No

INVENTOR INFORMATION

Inventor Authority Type:: Inventor
Primary Citizenship Ctry:: US
Given Name:: Abu K.
Family Name:: Eghan
Street:: 6572 Springpath Lane
City:: San Jose
State or Province:: CA
Postal or Zip Code:: 95124-4549

Inventor Authority Type:: Inventor
Primary Citizenship Ctry:: US
Given Name:: Lan H.
Family Name:: Hoang
Street:: 38848 Bell Street
City:: Fremont
State or Province:: CA
Postal or Zip Code:: 94586

09879875-061101

CORRESPONDENCE INFORMATION

Correspondence Customer Number:: 24309

REPRESENTATIVE INFORMATION

Representative Customer Number::	24309	
---	--------------	--

ASSIGNEE INFORMATION

Assignee Name:: Xilinx, Inc.
Street:: 2100 Logic Drive
City:: San Jose
State or Province:: California
Postal or Zip Code:: 95124

T0T50"5486Z860